

PATENT ABSTRACTS OF JAPAN

(11)Publication number : **2003-050459**

(43)Date of publication of application : **21.02.2003**

(51)Int.CI.

G03F 7/004
G03F 7/031
H05K 3/06
H05K 3/18

(21)Application number : **2001-239622**

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(22)Date of filing : **07.08.2001**

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(54) PHOTORESISTIVE RESIN COMPOSITION, PHOTORESISTIVE ELEMENT, METHOD FOR PRODUCING RESIST PATTERN AND METHOD FOR PRODUCING PRINTED WIRING BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a photosensitive resin composition excellent in photosensitivity, resolution, adhesion and solubility in a developing solution and a photosensitive element using the composition.

SOLUTION: The photosensitive resin composition comprises (A) a binder polymer, (B) a photopolymerizable monomer containing an ethylenically unsaturated group, (C) a polycyclic aromatic hydrocarbon, (D) a photopolymerization initiator and (E) a hydrogen donor. The photosensitive element is obtained by forming a resist layer comprising the photosensitive resin



composition on a support.

LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of
rejection]

[Kind of final disposal of application other than the
examiner's decision of rejection or application
converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of
rejection]

[Date of requesting appeal against examiner's
decision of rejection]

[Date of extinction of right]

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